BOMcheck.net

Full Material Declaration for attached parts list

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Diotec Semiconductor

Diotec Semiconductor AG

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 May 2009 [Approved on 21 December 2022, 14:42 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.19%	TITANIUM	7440-32-6	0.18%
			Nickel REACH Article 67 Exemption	7440-02-0	0.34%
			ALUMINIUM	7429-90-5	1.56%
			Silver	7440-22-4	2.07%
			Silicon	7440-21-3	95.85%
Die attach	Sn-Pb solder	25.96%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead EU RoHS Exemption 7(a) Exempt from other regulatory requirements Exempt from other regulatory requirements	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	47.63%	Carbon black	1333-86-4	0.15%
			Epoxy resin 89	26335-32-0	11.5%
			Quartz sand	60676-86-0	88.35%
Leadfinish	Tin plating	0.26%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	25.96%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
TOLL / HSOF-8	TOLL / HSOF-8	0.75	g